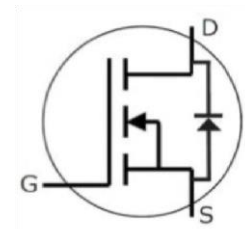
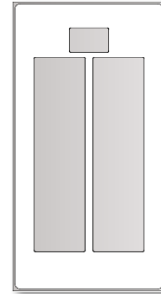


# CPM2-1200-0040A

## Wolfspeed SiC Gen 2 MOSFET

### Description

This is the Wolfspeed's 2nd generation of high performance silicon carbide MOSFET in a packageless bare die format to be implemented into any custom module design. The high blocking voltage with low on-resistance, high speed switching with low capacitance make this MOSFET ideal for high frequency switching application including solar inverters and motor drives.



Package Types: Bare Die  
PN's: CPM2-1200-0040A

### Features

- Enhanced 2nd Generation SiC MOSFET
- High blocking voltage with low on-resistance
- High speed switching with low capacitance
- Fast intrinsic diode with low reverse recovery

### Applications

- UPS
- Solar Inverters
- SMPS
- DC/DC Converters
- Motor Drives

### Absolute Maximum Ratings

Stress beyond those listed under absolute maximum ratings may damage the device.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage, across $T_{vj}$	$V_{DS(max)}$	1200	V
Maximum Gate-Source Voltage, Peak Transient Capability	$V_{GS(max)}$	-10/+25	V
Continuous Drain Current, $V_{GS} = 15V$ , assumes die packaged in TO-247 package with $R_{th(j-c)} < 0.38 \text{ K/W}$	$I_D$	$T_c = 25^\circ\text{C}$	A
		$T_c = 100^\circ\text{C}$	
Pulsed Drain Current, $t_p$ limited by $T_{vj(max)}$	$I_D(pulse)$	170	A
Virtual Junction and Storage Temperature	$T_{vj}, T_{stg}$	-55 to 175	$^\circ\text{C}$
Maximum Processing Temperature, in non-reactive ambient	$T_{proc}$	325	$^\circ\text{C}$

### Recommended Operating Conditions

Parameter	Symbol	Rating	Unit
Recommended Operating Gate - Source Voltage	$V_{GS(op)}$	-5/+20	V

**Electrical Characteristics ( $T_{VJ} = 25^{\circ}\text{C}$ )**

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200			V	$V_{GS} = 0\text{ V}$ , $I_D = 100\text{ }\mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	2.0	3.1	4.0	V	$V_{DS} = V_{GS}$ , $I_{DS} = 10\text{ mA}$
			2.3		V	$V_{DS} = V_{GS}$ , $I_{DS} = 10\text{ mA}$ , $T_{VJ} = 175^{\circ}\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$		1	100	$\mu\text{A}$	$V_{DS} = 1200\text{ V}$ , $V_{GS} = 0\text{ V}$
Gate-Source Leakage Current	$I_{GSS}$		10	250	nA	$V_{GS} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$
Drain-Source On-State Resistance	$R_{DS(on)}$		40	52	m $\Omega$	$V_{GS} = 20\text{ V}$ , $I_D = 40\text{ A}$
			90			$V_{GS} = 20\text{ V}$ , $I_D = 40\text{ A}$ , $T_{VJ} = 175^{\circ}\text{C}$
Transconductance	$g_{fs}$		18		S	$V_{DS} = 20\text{ V}$ , $I_{DS} = 40\text{ A}$
			17			$V_{DS} = 20\text{ V}$ , $I_{DS} = 40\text{ A}$ , $T_{VJ} = 175^{\circ}\text{C}$
Input Capacitance	$C_{iss}$		2287		pF	$V_{GS} = 0\text{ V}$ , $V_{DS} = 1000\text{ V}$ $f = 1\text{ Mhz}$ $V_{AC} = 25\text{ mV}$
Output Capacitance	$C_{oss}$		157			
Reverse Transfer Capacitance	$C_{rss}$		8			
$C_{oss}$ Stored Energy	$E_{oss}$		85		$\mu\text{J}$	$V_{DS} = 1000\text{ V}$ , $f = 1\text{ Mhz}$
Internal Gate Resistance	$R_{G(int)}$		2.7		$\Omega$	$f = 1\text{ Mhz}$ , $V_{AC} = 25\text{ mV}$
Gate to Source Charge	$Q_{gs}$		29		nC	$V_{DS} = 800\text{ V}$ , $V_{GS} = -5\text{ V}/20\text{ V}$ $I_{DS} = 40\text{ A}$ Per IEC60747-8-4 pg 21
Gate to Drain Charge	$Q_{gd}$		45			
Total Gate Charge	$Q_g$		131			

**Reverse Diode Characteristics ( $T_{VJ} = 25^{\circ}\text{C}$ )**

Characteristics	Symbol	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage	$V_{SD}$	4.2		V	$V_{GS} = -5\text{ V}$ , $I_{SD} = 20\text{ A}$
		3.7		V	$V_{GS} = -5\text{ V}$ , $I_{SD} = 20\text{ A}$ , $T_{VJ} = 175^{\circ}\text{C}$
Reverse Recovery Time	$t_{rr}$	63		ns	$V_{GS} = -5\text{ V}$ , $I_{SD} = 40\text{ A}$ , $V_R = 800\text{ V}$ $\text{dif/dt} = 1406\text{ A}/\mu\text{s}$
Reverse Recovery Charge	$Q_{rr}$	964		nC	
Peak Reverse Recovery Current	$I_{rrm}$	18		A	

## Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

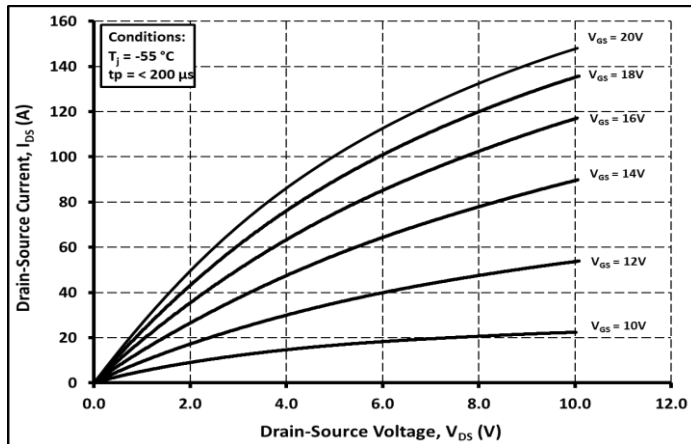


Figure 1.

Output Characteristics  $T_{vj} = -55\text{ }^{\circ}\text{C}$

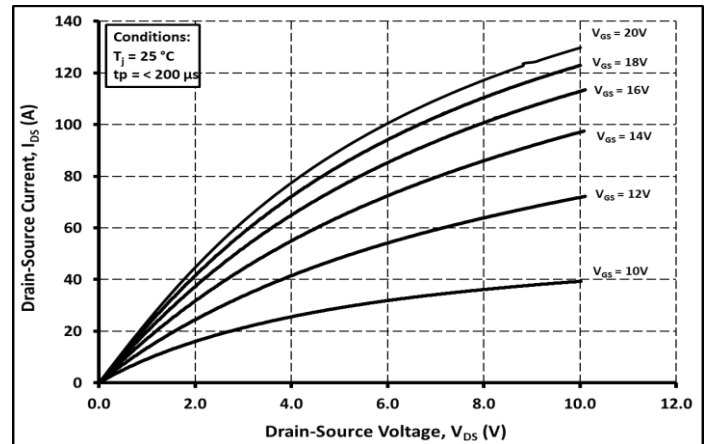


Figure 2.

Output Characteristics  $T_{vj} = 25\text{ }^{\circ}\text{C}$

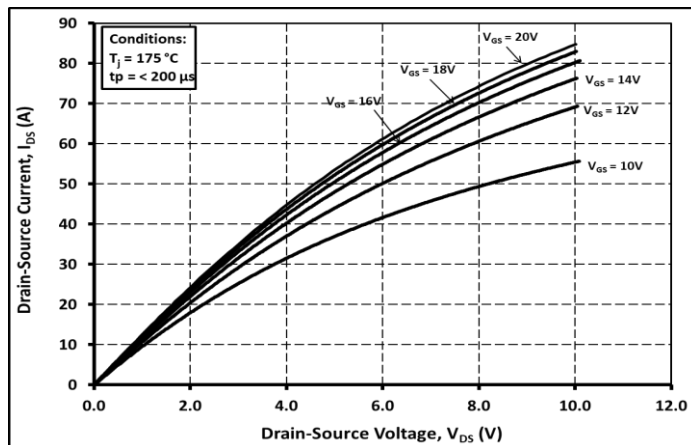


Figure 3.

Output Characteristics  $T_{vj} = 175\text{ }^{\circ}\text{C}$

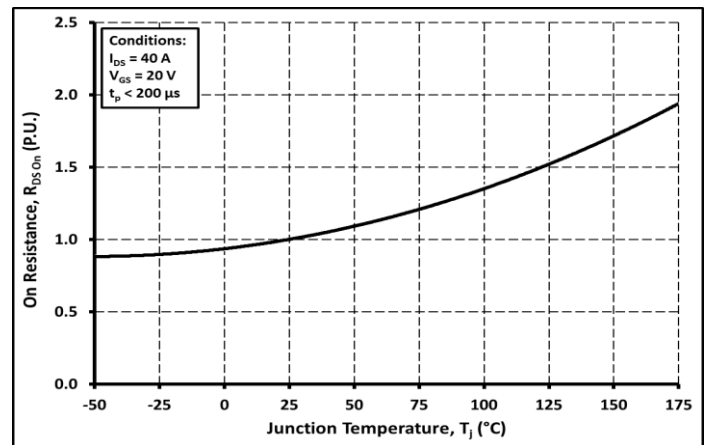


Figure 4.

Normalized On-Resistance vs. Temperature

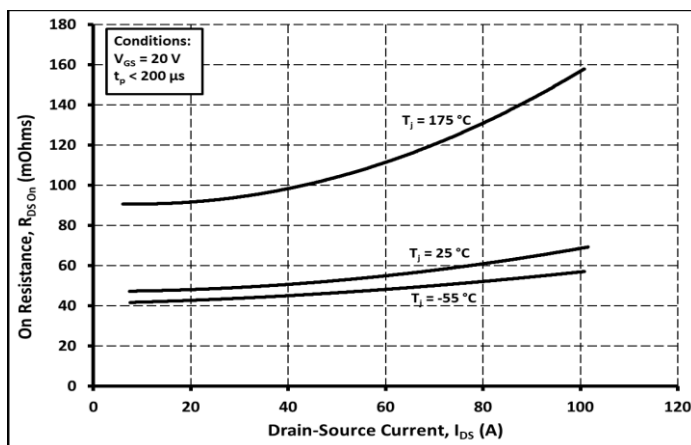


Figure 5.

On-Resistance vs. Drain Current For Various Temperatures

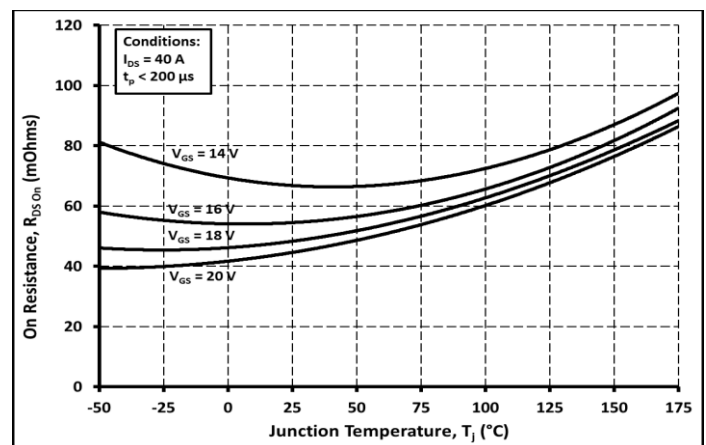


Figure 6.

On-Resistance vs. Temperature For Various Gate Voltages

## Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

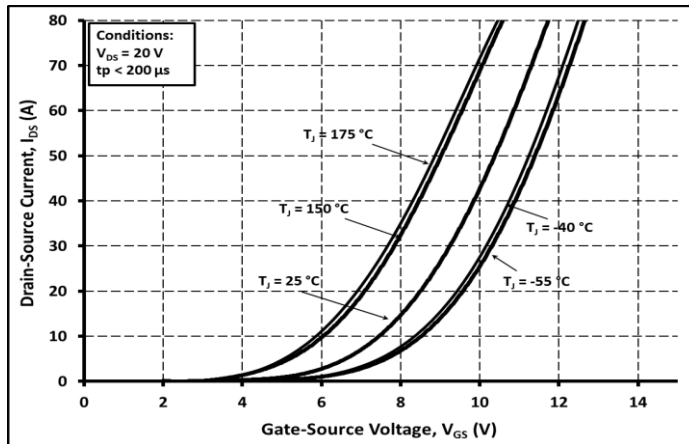


Figure 7.

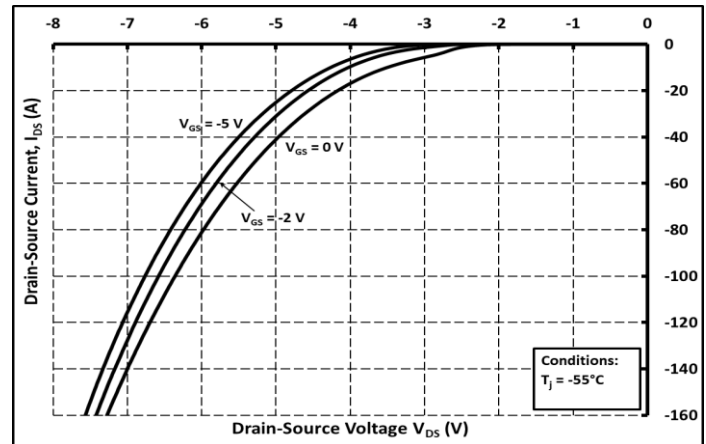


Figure 8.

Transfer Characteristic For Various Junction Temperatures

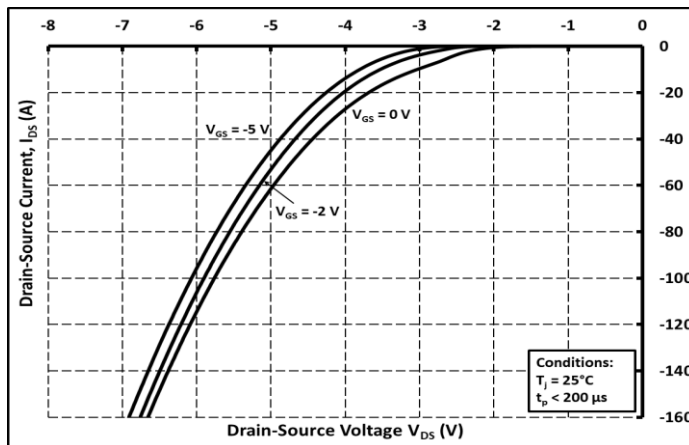


Figure 9.

Body Diode Characteristic at  $T_{vj} = -55\text{ }^{\circ}\text{C}$

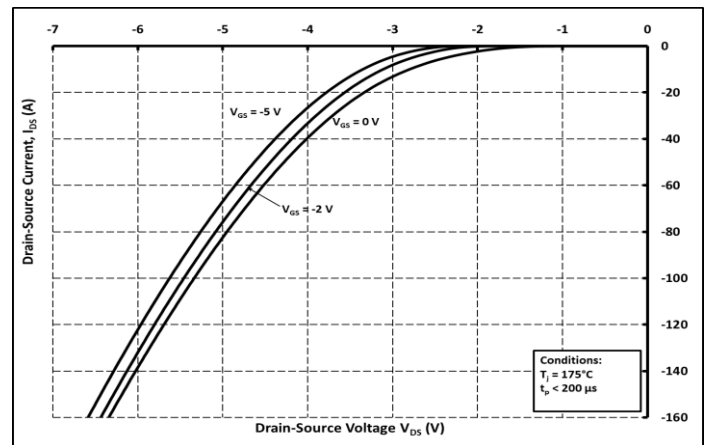


Figure 10.

Body Diode Characteristic at  $T_{vj} = 25\text{ }^{\circ}\text{C}$

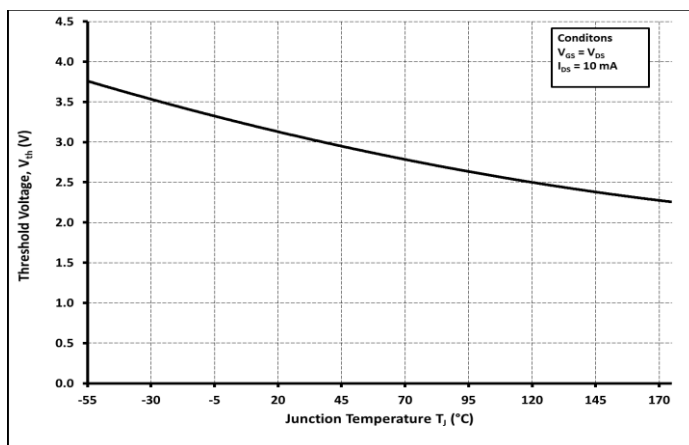


Figure 11.

Body Diode Characteristic at  $T_{vj} = 175\text{ }^{\circ}\text{C}$

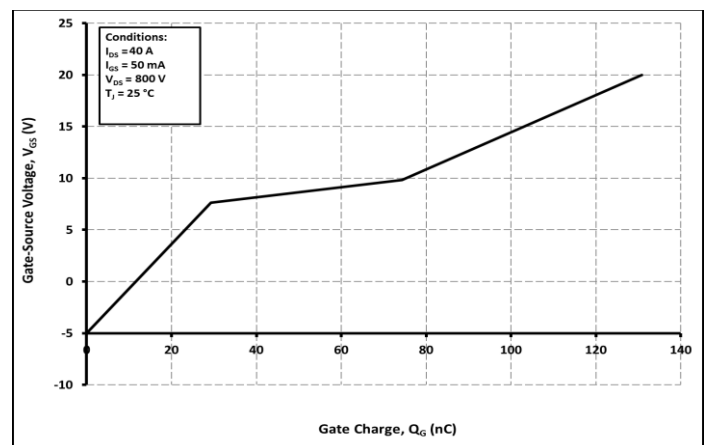


Figure 12.

Threshold Voltage vs. Temperature

Gate Charge Characteristics

## Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

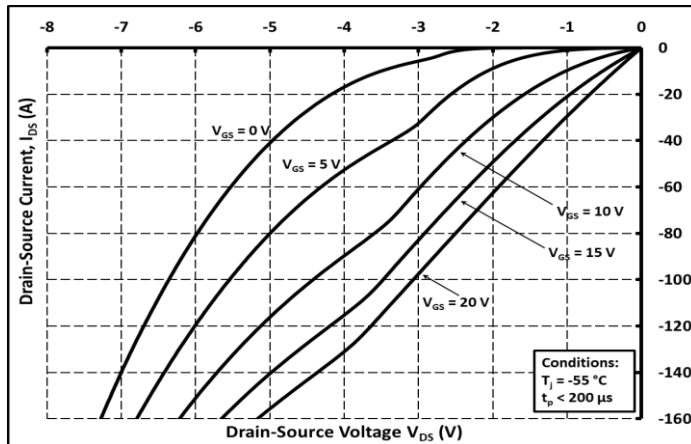


Figure 13.

3rd Quadrant Characteristic at  $T_{vj} = -55\text{ }^{\circ}\text{C}$

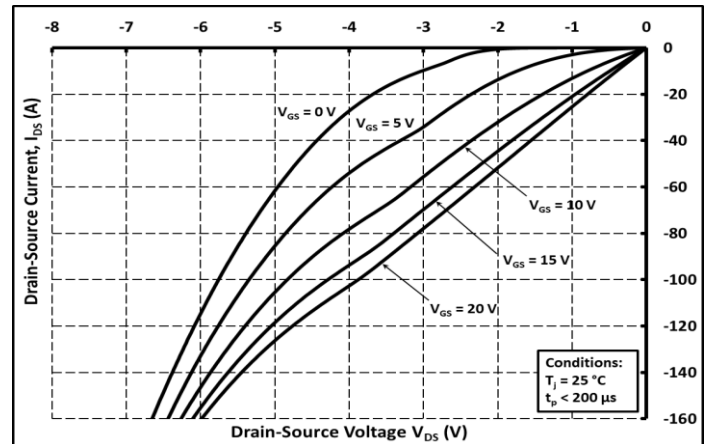


Figure 14.

3rd Quadrant Characteristic at  $T_{vj} = 25\text{ }^{\circ}\text{C}$

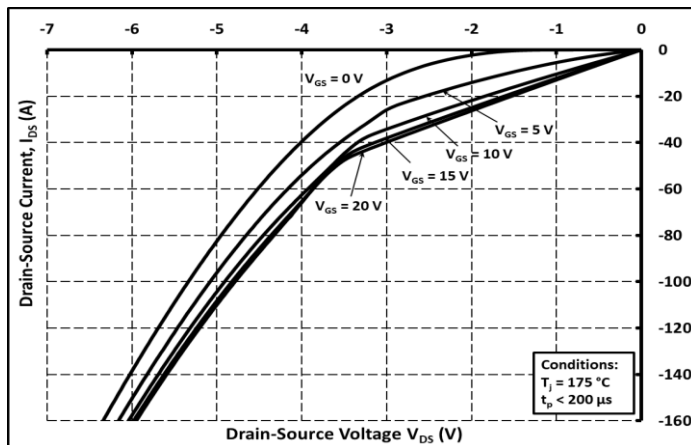


Figure 15.

3rd Quadrant Characteristic at  $T_{vj} = 175\text{ }^{\circ}\text{C}$

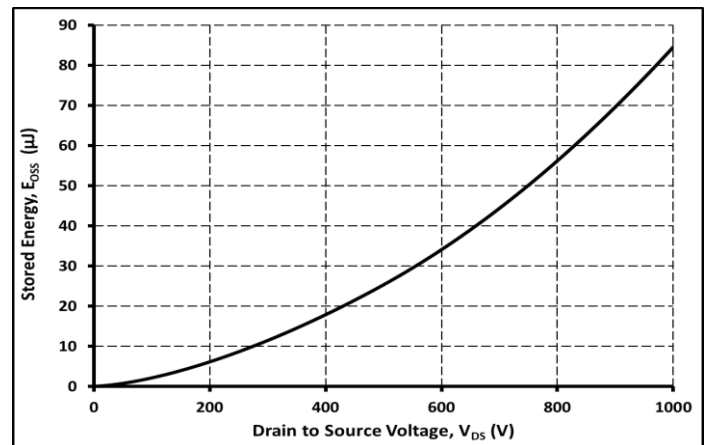


Figure 16.

Output Capacitor Stored Energy

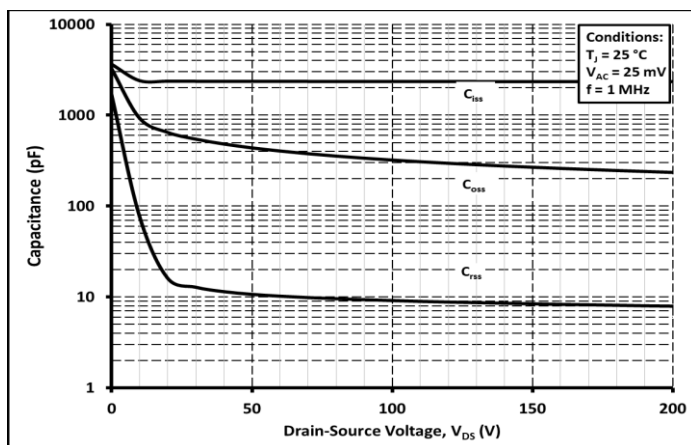


Figure 17.

Capacitances vs. Drain-Source Voltage (0-200V)

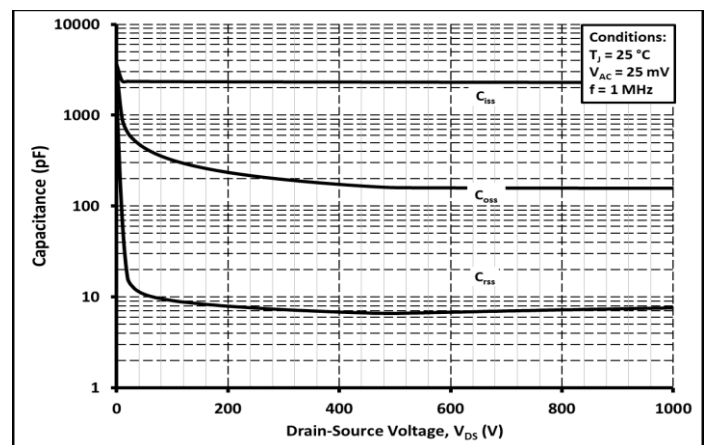
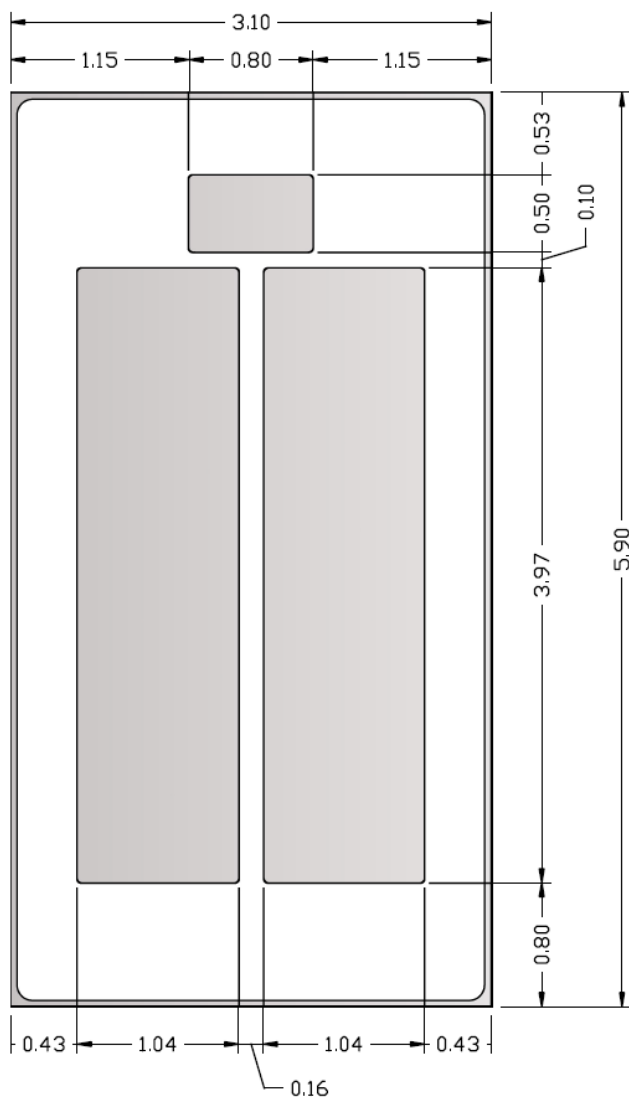


Figure 18.

Capacitances vs. Drain-Source Voltage (0-1200V)

**Product Dimensions CPM2-1200-0040A****Product Dimensions CPM2-1200-0040A**

Parameter	Typical	Units
Die Size (L x W)	3.10 x 5.90	mm
Exposed Source Pad Metal Dimensions	1.04 x 3.97 (x2)	mm
Gate Pad Dimensions	0.80 x 0.50	mm
Chip Thickness <sup>1</sup>	180 ± 40	μm
Frontside (Source) metalization (Al)	4	μm
Frontside (Gate) metalization (Al)	4	μm
Backside (Drain) metalization (Ni:Au)	0.8 / 0.1	μm

<sup>1</sup> SiC wafer thickness



Product Ordering Information

Order Number	Description	Package
CPM2-1200-0040A-FY6	SiC MOSFET G3 IND 1200V/40mO UV MLT	Bare Die Product

Revision History

Revision History	Date of Change	Brief Summary
1	11/2020	Initial Release
2	12/22/2023	Template updated

## Notes & Disclaimer

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